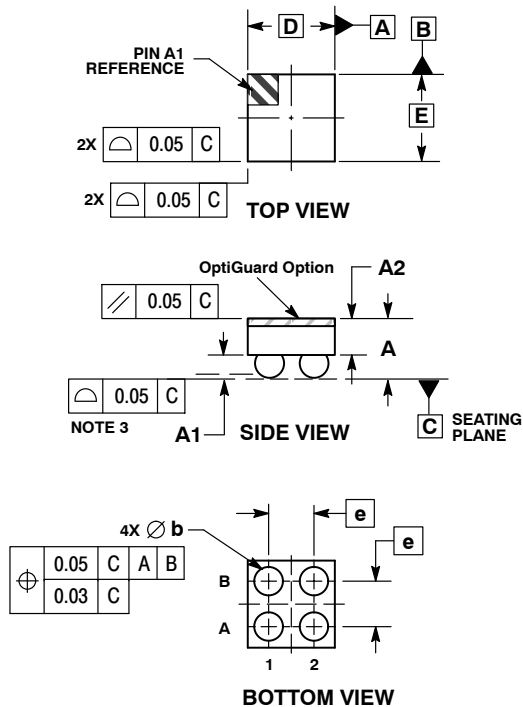




SCALE 4:1

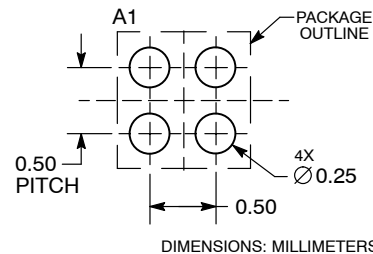
WLCSP4, 0.96x0.96
CASE 567AW
ISSUE O

DATE 26 JUL 2010


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.56	0.72
A1	0.21	0.27
A2	0.42	REF
b	0.29	0.35
D	0.96	BSC
E	0.96	BSC
e	0.50	BSC

**RECOMMENDED
SOLDERING FOOTPRINT***


*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP4, 0.96X0.96	PAGE 1 OF 1

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